

ABSTRACT OF THE DISCLOSURE

A semiconductor wafer transfer apparatus includes a wafer supporting block to support a semiconductor wafer, a casing which is formed along a moving path of the wafer supporting block and having a guiding slot through which a part of the wafer supporting block passes, a driving part which is accommodated in the casing and moves the wafer supporting block, a connection part which connects the driving part with the wafer supporting block, and a shield part which shields the driving part from the guide slot. Accordingly, dust and particles generated inside the casing is effectively prevented from leaking out through the guide slot.